



Part No. :XL-0201UWC

XL-0201UWC



Technical Data

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包装

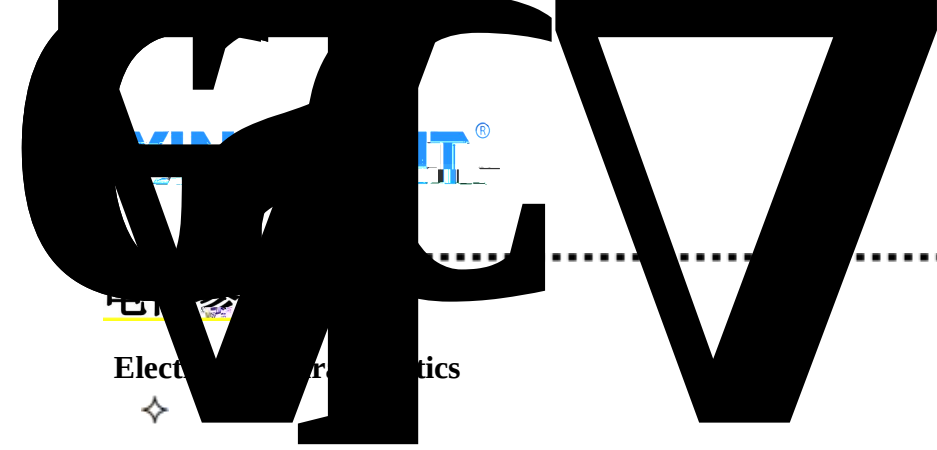
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焊接指导

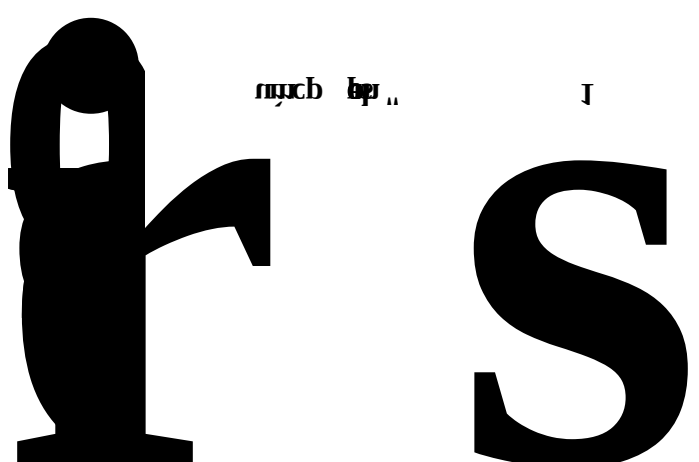
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Electronics

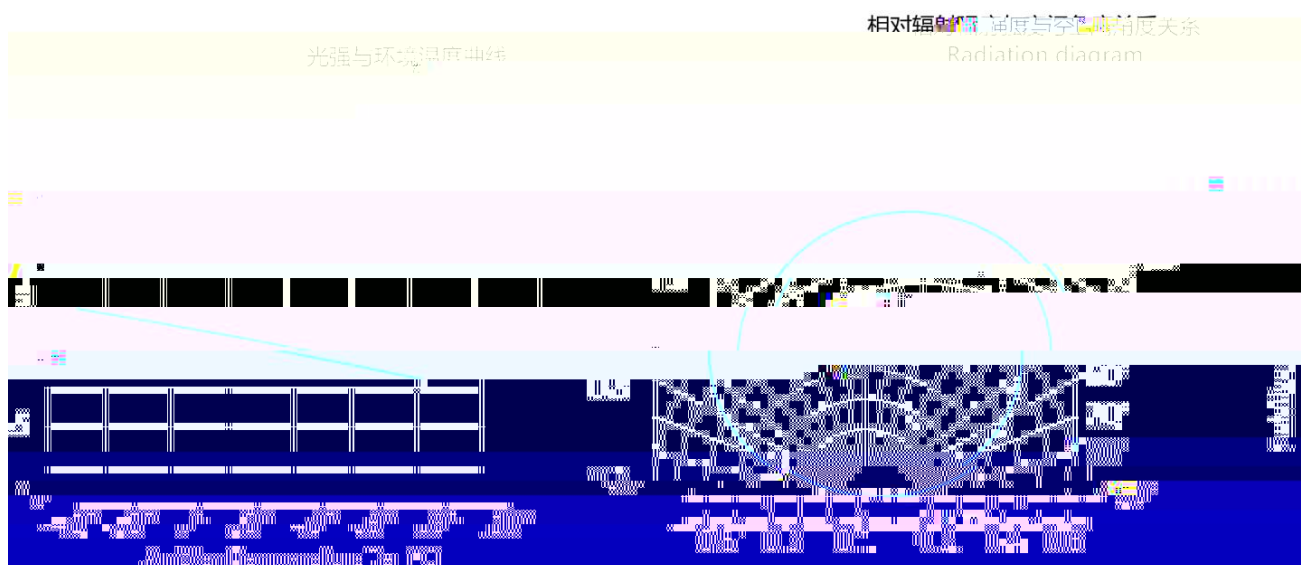
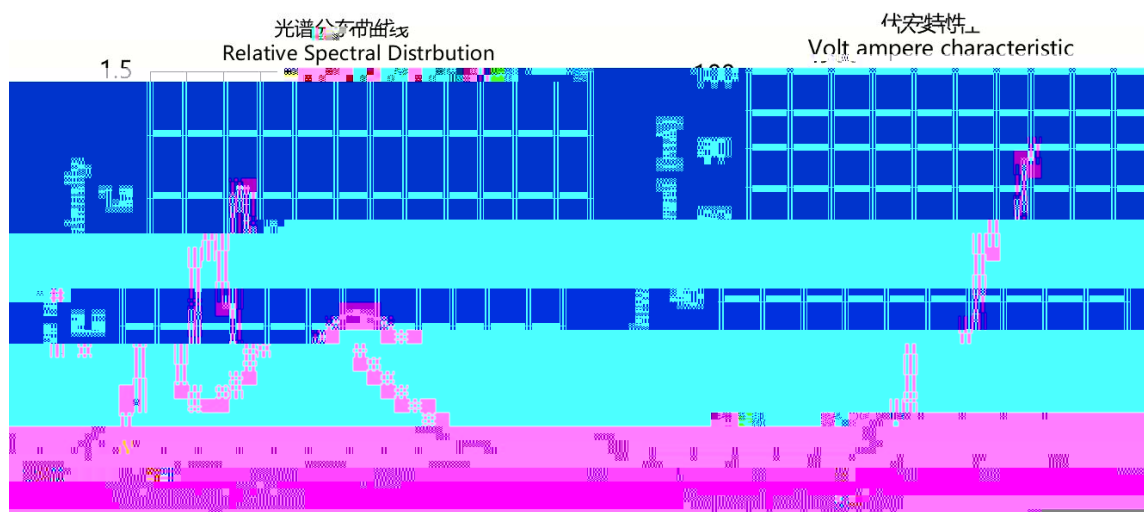


.....

Bin Code	CIE-X	CIE-Y	Bin Code	CIE-X	CIE-Y	Bin Code	CIE-X	CIE-Y	Bin Code	CIE-X	CIE-Y	Bin Code	CIE-X	CIE-Y
	0.3099	0.3509		0.3202	0.3532		0.3290	0.3690		0.3381	0.3762		0.3005	0.3415
	0.3107	0.3450		0.3290	0.3614		0.3290	0.3614		0.3379	0.3689		0.3017	0.3360
F5	0.3201	0.3542	G5	0.3290	0.3690	H5	0.3379	0.3689	I5	0.3472	0.3764	E5	0.3107	0.3450
	0.3196	0.3602		0.3196	0.3602		0.3381	0.3762		0.3480	0.3840		0.3099	0.3509
	0.3107	0.3450												
F6			G6											

典型特性曲线

Typical Characteristics Curves



2505 Ĺ/Note If not otherwise indicated the test environment temperature is 2505 Ĺ

Reliability experiment

Class	Test item	Testing environment	Testing time	Reference standard
Endurance test	Working life	20mA Continuous lighting at the maximum rated current at room temperature:Test it at 20mA.	1000 -24) -24hours 1000 hours +72 +72hours	MIL-STD-750D:1026 MIL-STD-883D:1005 JIS C 7021:B-1
	High temperature and high humidity storage	IR-Reflow In-Board, 2 Times Ta= 85 $\pm$ 5 $\text{^{\circ}N}$, RH= 90 95%	240 $\pm$ 2) $\pm$ 2 2hours)	MIL-STD-202F:103B JIS C 7021:B-11
	High-temperature storage	Ta= 85 $\pm$ 5 $\text{^{\circ}N}$	1000 -24 +72) -24hours+72hours	MIL-STD-883D:1008 JIS C 7021:B-10
	Low temperature	Ta= -40 $\pm$ 5 $\text{^{\circ}N}$		JIS C 7021:B-12
Environmental testing	Cold and hot cycle	105 $\text{^{\circ}N}$ 25 $\text{^{\circ}N}$ -55 $\text{^{\circ}N}$ 25 $\text{^{\circ}N}$ 30mins 5mins 30mins 5mins	100 100 Circles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010
	Hot and cold impact	IR-Reflow In-Board, 2 Times 100 $\pm$ 5 $\text{^{\circ}N}$ -40 $\text{^{\circ}N}$ $\pm$ 5 $\text{^{\circ}N}$ 20mins 20mins	100 100 Circles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1011
	Anti-tin test	T.sol= 260 $\pm$ 5 $\text{^{\circ}N}$	10 $\pm$ 1secs 2 2times	MIL-STD-202F:210A MIL-STD-750D:2031 JIS C 7021:A-1
	Infrared reflowwelding There is lead process	heat up speed(183 $\text{^{\circ}N}$) 3 $\text{^{\circ}N}$ / keep temperature 125($\pm$ 25) $\text{^{\circ}N}$ 120 keep temperature 183 $\text{^{\circ}N}$ 60-150 maximum temperature 235 $\text{^{\circ}N}$ +5/-0 $\text{^{\circ}N}$ keep 235 $\text{^{\circ}N}$ +5/-0 $\text{^{\circ}N}$ 10-15 cooling rate 6 $\text{^{\circ}N}$ /	-----	MIL-STD-750D:2031.2 J-STD-020C
	Infrared reflow welding Lead-free process	heat up speed(217 $\text{^{\circ}N}$) 3 $\text{^{\circ}N}$ / keep temperature 175($\pm$ 25) $\text{^{\circ}N}$ 180 keep temperature 217 $\text{^{\circ}N}$ 60-120 maximum temperature 255 $\text{^{\circ}N}$ +0/-5 $\text{^{\circ}N}$ keep 255 $\text{^{\circ}N}$ +0/-5 $\text{^{\circ}N}$ 5-10 cooling rate 6 $\text{^{\circ}N}$ /	-----	MIL-STD-750D:2031.2 J-STD-020C
	Weldability test	Soldering temperature T.sol= 235 $\pm$ 5 $\text{^{\circ}N}$ $\pm$ 5 $\text{^{\circ}N}$ Immersion speed 25 $\pm$ 2.5 mm/ loading rate $\geq$ 95% 95% Tin time: 2 $\pm$ 0.5 seconds	Immersion time 2 $\pm$ 0.5	MIL-STD-202F:208D MIL-STD-750D:2026 MIL-STD-883D:2003 IEC 68 Part 2-20 JIS C 7021:A-2



外形尺寸

Outline Dimension

- Remarks:
1.

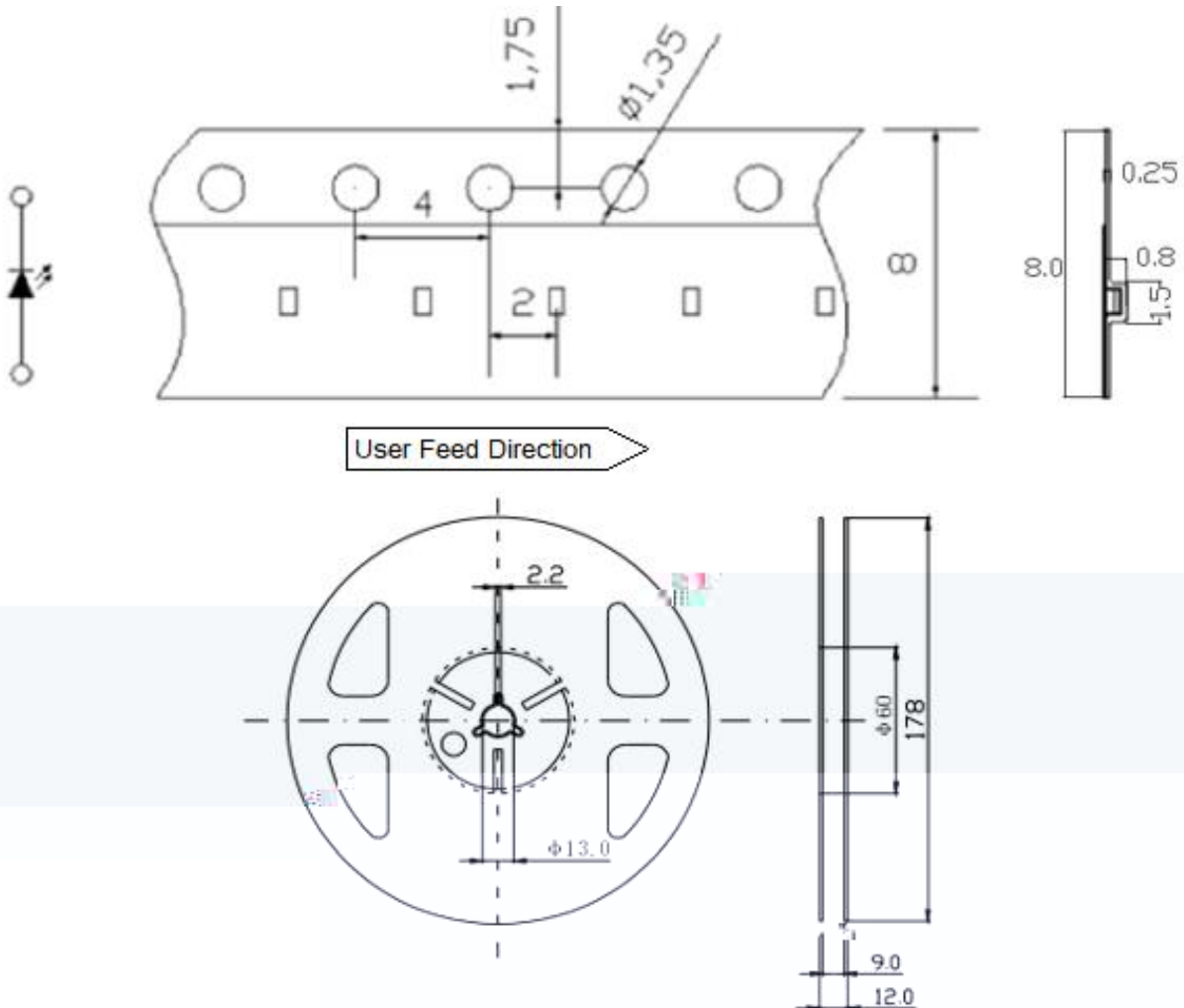
mm
- 1 Unit: mm
2.

0.10mm
2. Tolerance: 0.10mm unless otherwise spec`i`d

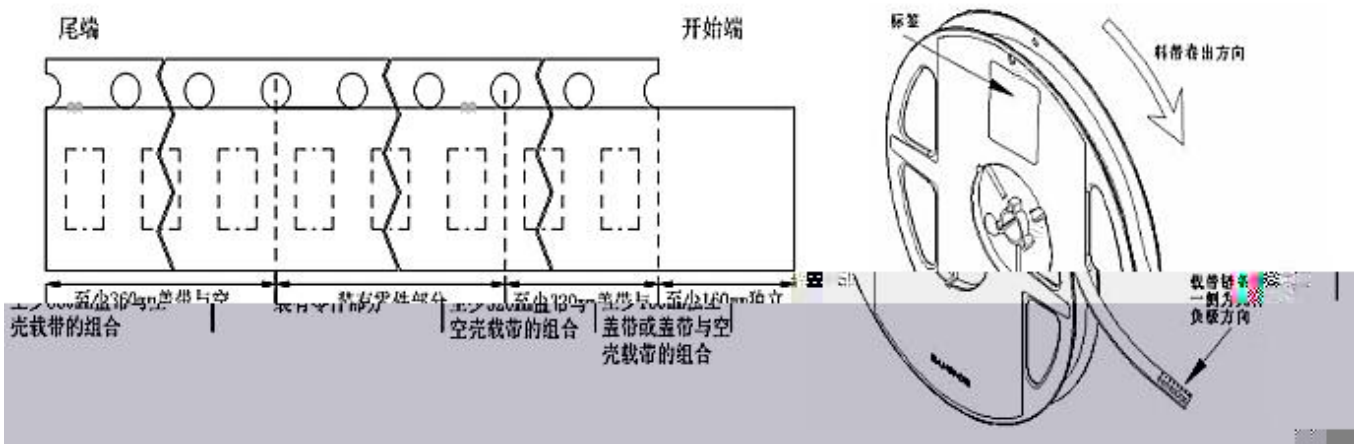
包装 (1)

Packaging (1)

载带与圆盘尺寸 Belt and disk dimensions



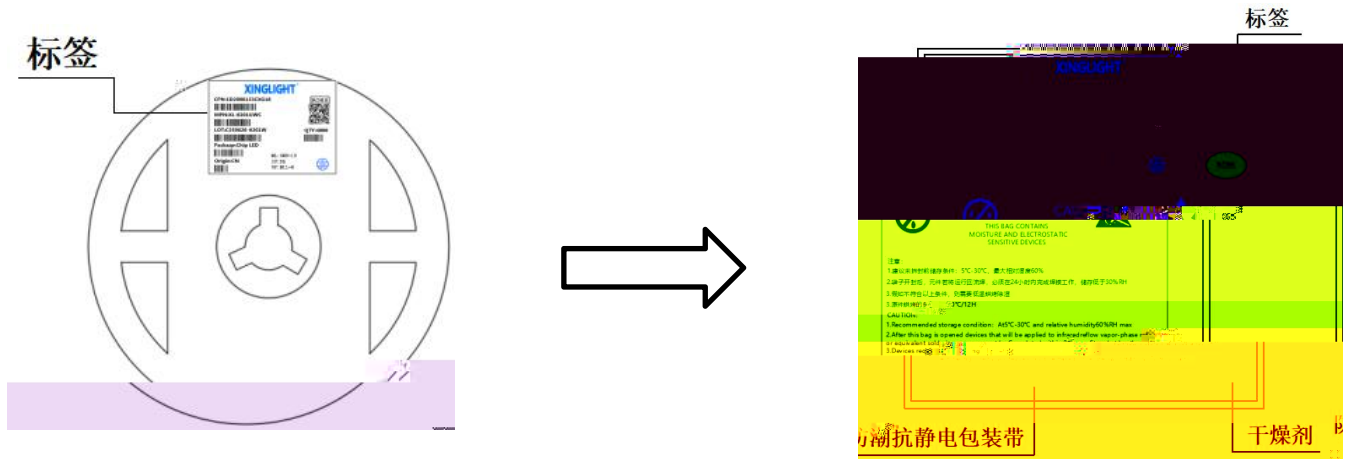
圆盘及载带卷出方向及空穴规格 Disk and carrier belt direction of roll and hole dimensions



装 (2)

ing (2)

Mo ure Proo d Antti-Electrostatic Foil Bag



O Cardboard Box



O Label Expantion

焊接指导 (1)

Guideline for Soldering (1)

1. 使用烙铁人手焊接

Hand Soldering

300 ℃

30 W

3 s

LED

⏏

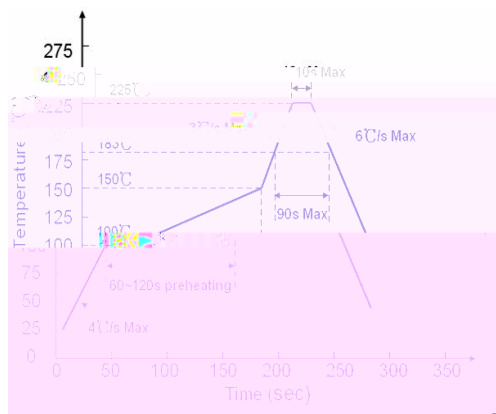
Manual welding is recommended only for repair and heavy industry situations. A soldering iron of less than 30W is recommended to be used in Hand Soldering. Please keep the temperature of the soldering iron under 300 ℃ while soldering. Each terminal of the LED is to go for less than 3 second and for one time only.

Be careful because the damage of the product is often started at the time of the hand soldering.

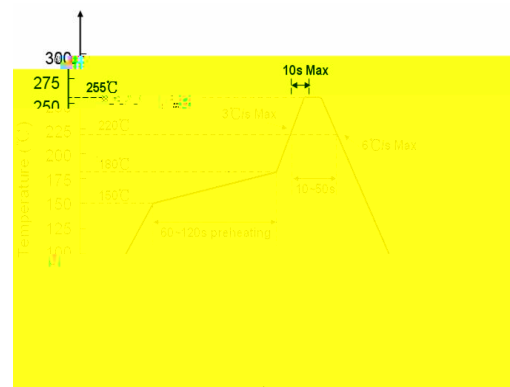
2. 回流焊接:

⏏

Reflow Soldering: Use the conditions shown in the under Figure of Pb-Free Reflow Soldering.



Lead process



lead free

⏏

Reflow soldering should not be done more than two times.

LED

⏏

Stress on the LEDs should be avoided during heating in soldering process.

⏏

After soldering, do not deal with the product before its temperature drop down to room temperature.

240 ± 5 ℃/6s

The recommended maximum welding temperature for the product is 240 ± 5 ℃/6s



3. 清洗:

Cleaning

山

30Ñ

3

50Ñ

30

LED

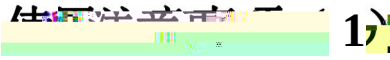
山

300W

LED E. 山

LED

山



Precautions (1)

1. 贮存:

Storage

1

山

Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to a minimum.

1

30Ñ

40%RH

使用聲音

Area

3. 設計建議

Design Consideration

LED

山

A

LED

B

LED

